

P1-09 Fabrication method of SPAD sensor for automotive LiDAR to compensate the process fluctuation by feedforward system

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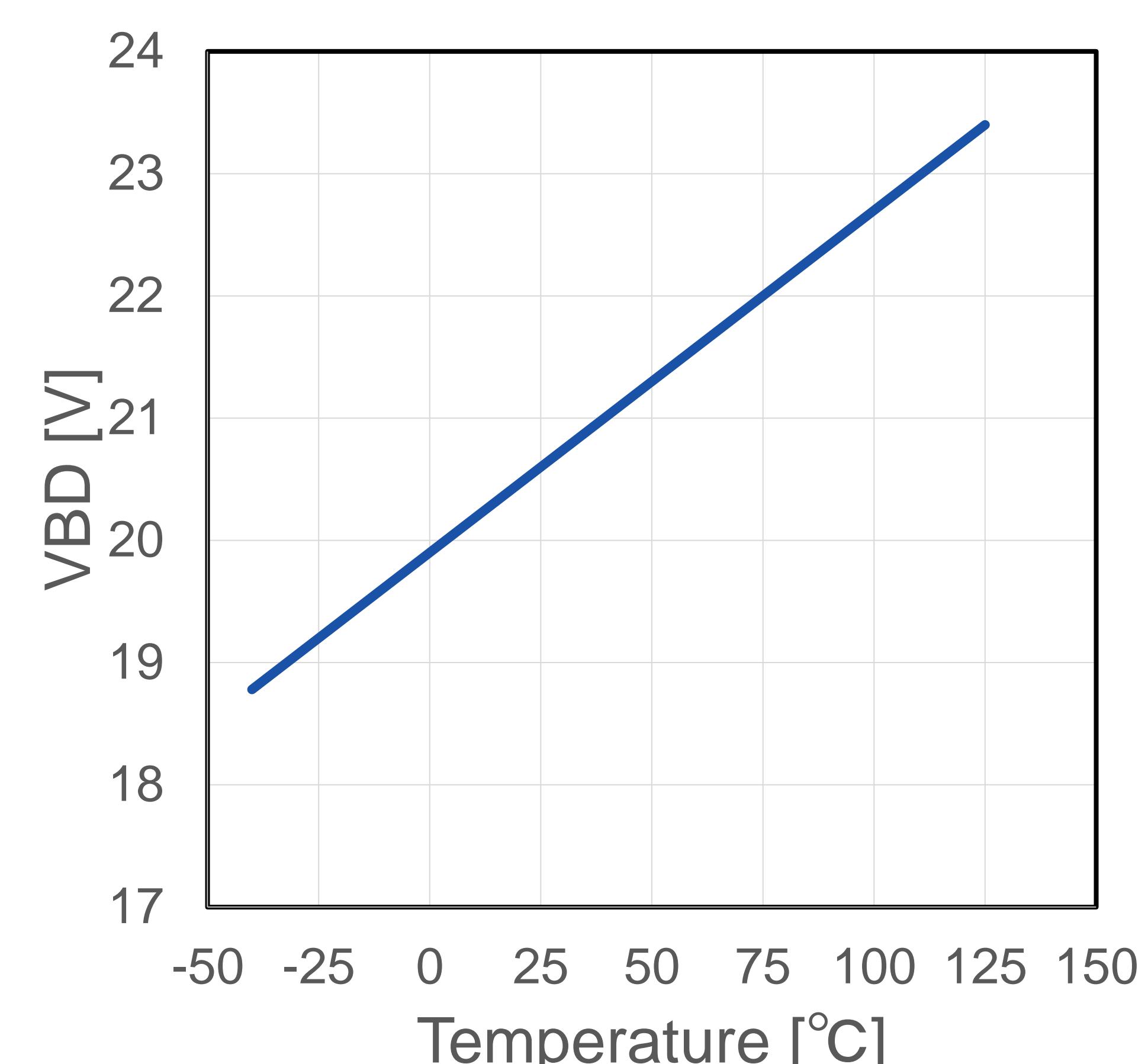
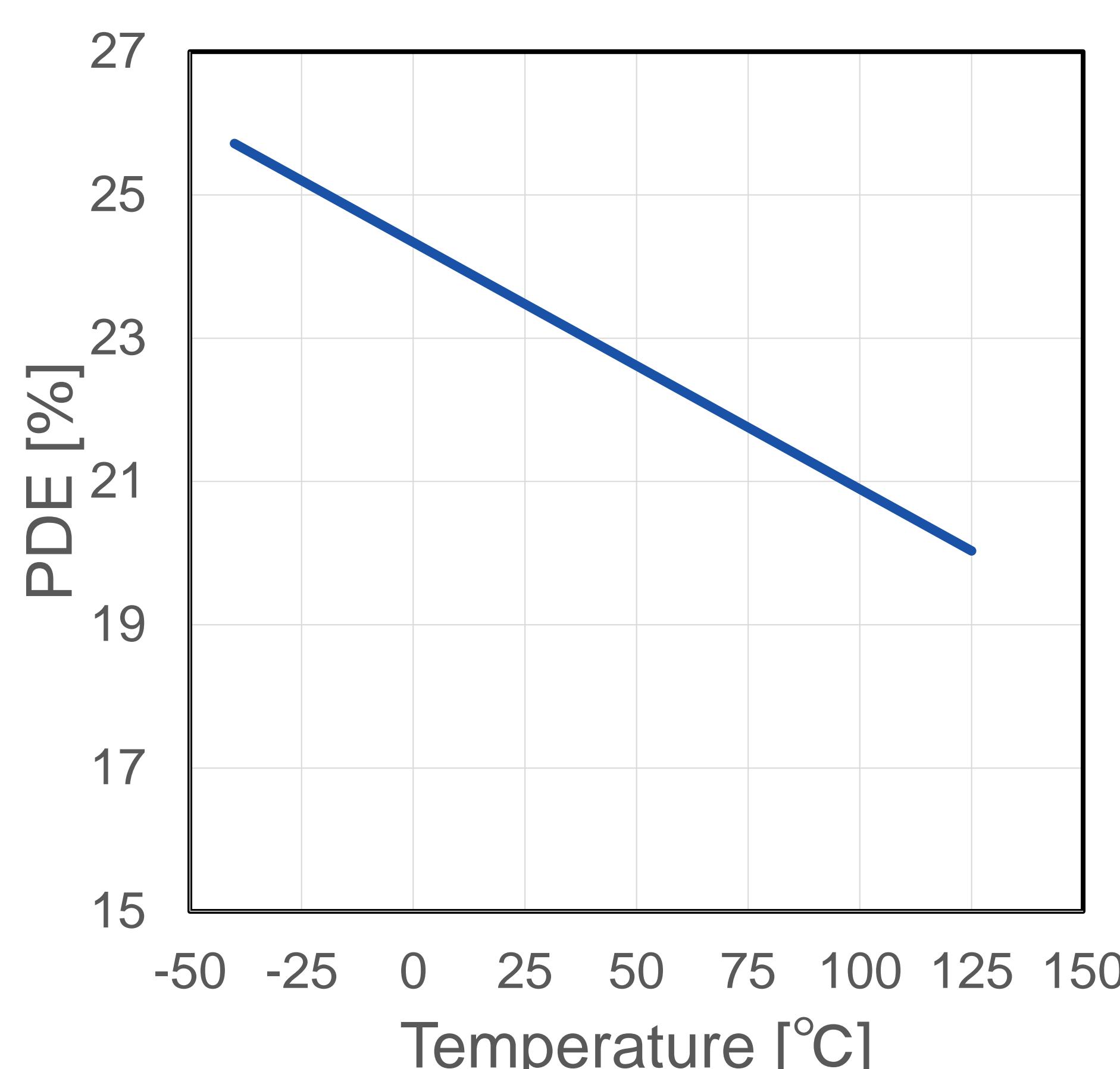
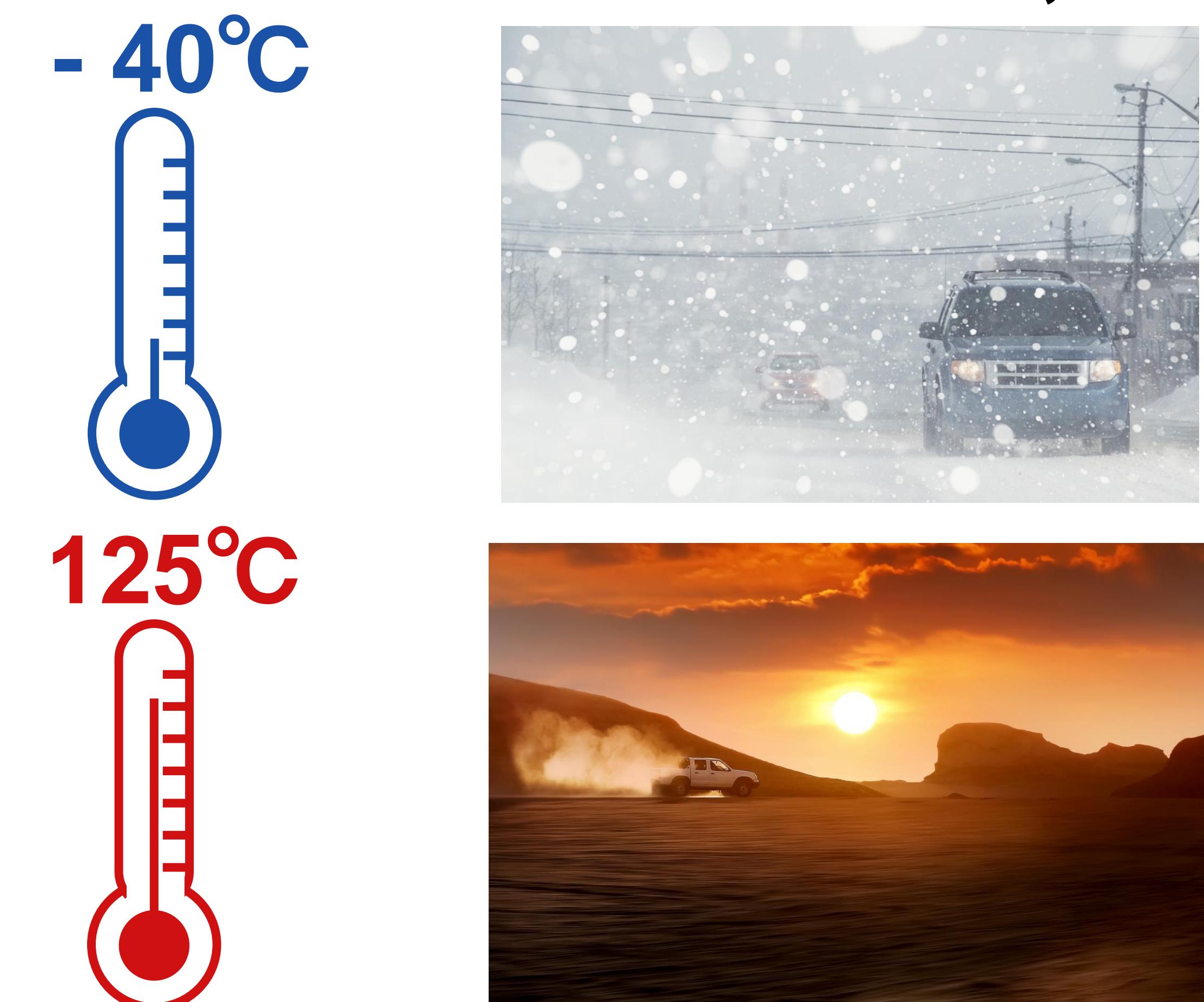
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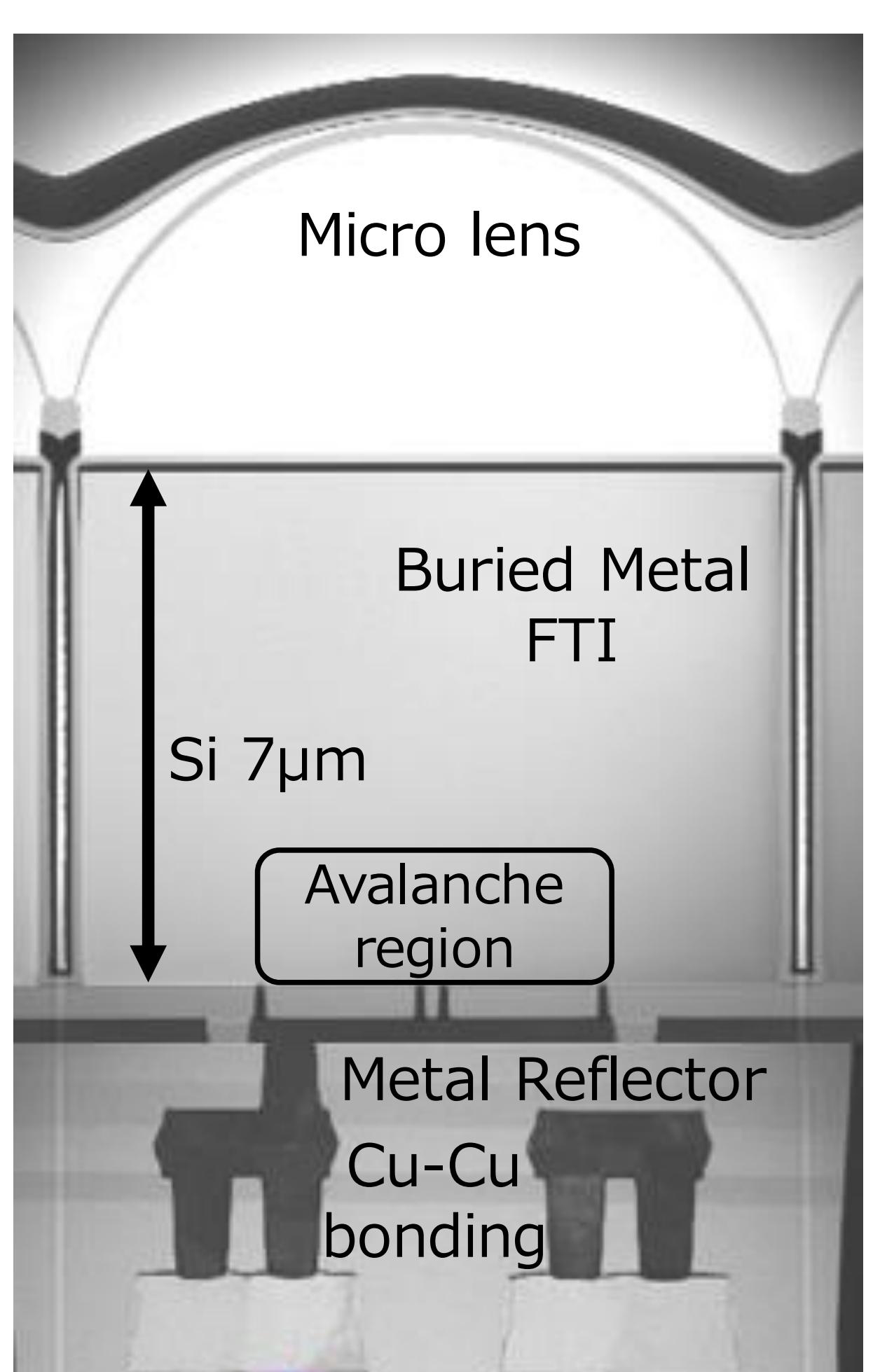
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Requirement from Automotive Electronics Council(AEC)

For the automotive, temperature range is required from -40°C to 125°C



SPAD Structure and Process Fluctuation



Anneal/Deposit

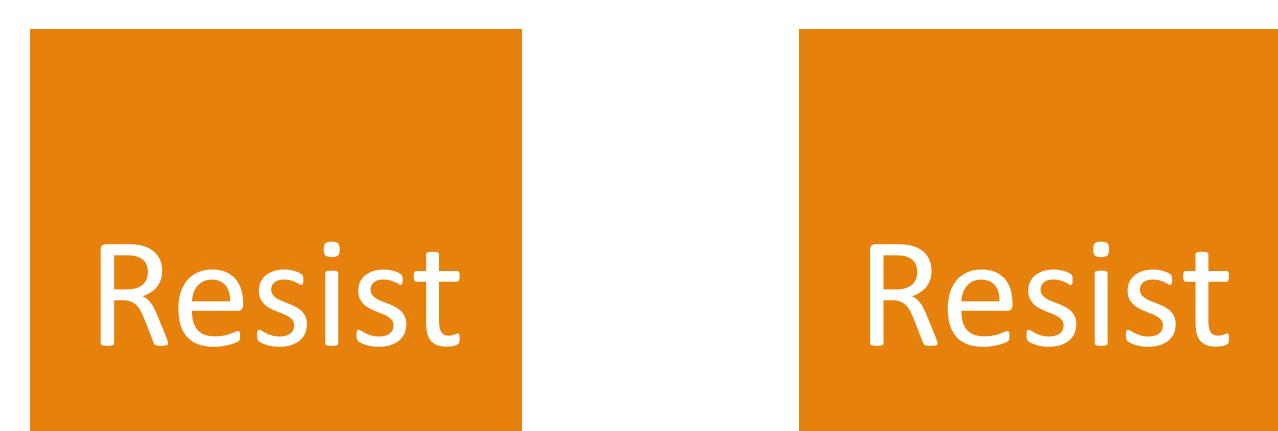


Film

Si Substrate

Anneal Temperature
Film Thickness

Photo Lithography



Si Substrate
Film

Aperture Width
Resist Taper

Ion Implant

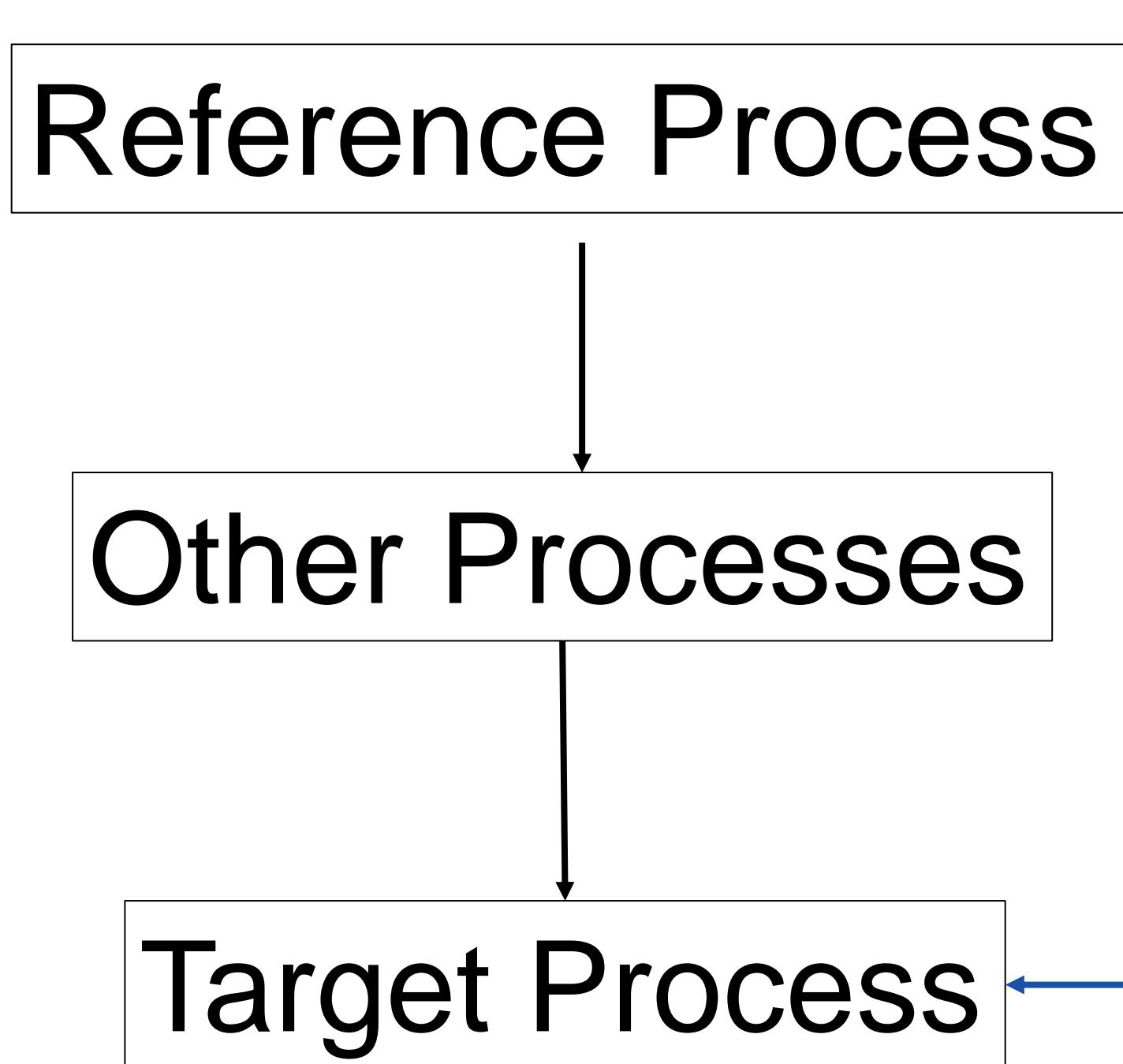


Si Substrate
Film

Peak Concentration
Tail Profile

Process Feedforward System

Reduce the PDE and VBD variation by process feedforward system



Monitor the Ref. Process Performance
Tune the Target Process Condition

